

CLAIMS

What is claimed is:

- 1 1. A device for maintaining a microprocessor in a desired relationship with a printed wiring
2 board while limiting the transmission of shock and vibrational motion to and from the processor,
3 comprising:
4 a printed wiring board;
5 a processor; and
6 a dynamic isolating mount compressed between said printed wiring board and said
7 processor;
8 said processor maintaining said dynamic isolating mount in a compressed state such
9 that said dynamic isolating mount bears on said printed wiring board.
- 1 2. The device of claim 1 further comprising interposer columns.
- 1 3. The device of claim 1 wherein said dynamic isolating mount comprises a continuous piece
2 that contacts the periphery of the processor.
- 1 4. The device of claim 1 wherein said dynamic isolating mount comprises a predetermined
2 number of pieces that contact the periphery of the processor.
- 1 5. The device of claim 1 wherein said dynamic isolating mount comprises material resistant to
2 temperatures below 130°C.

1 6. The device of claim 1 wherein the dynamic isolating mount possesses a loss factor of at
2 least 0.010.

1 7. The device of claim 1 wherein the dynamic isolating mount is manufactured by
2 Sorbothane.

1 8. The device of claim 1 wherein the dynamic isolating mount is critically damped.

1 9. A method for limiting shock/vibrational motion of a microprocessor comprising placing a
2 dynamic isolating mount between a processor and printed wiring board.

1 10. The method of claim 9 wherein the dynamic isolating mount is resistant to temperatures
2 below 130°C.

1 11. The method of claim 9 wherein the dynamic isolating mount possesses a loss factor of at
2 least 0.010.

1 12. The method of claim 9 wherein the dynamic isolating mount is manufactured by
2 Sorbothane.

1 13. A method for preventing cracking of the ceramic body of a microprocessor comprising
2 placing a dynamic isolating mount on a printed wiring board where said printed wiring board
3 contacts said processor.

1 14. The method of claim 13 wherein the dynamic isolating mount is resistant to temperatures
2 below 130°C.

1 15. The method of claim 13 wherein the dynamic isolating mount possesses a loss factor of at
2 least 0.010.

1 16. The method of claim 13 wherein the dynamic isolating mount is manufactured by
2 Sorbothane.

1 17. A computer system comprising:
2 a chassis;
3 an input device; and
4 a system board mounted inside said chassis, wherein said system board includes a
5 component mounted thereto using a vibration isolator comprising:
6 a processor;
7 a first component; and
8 a dynamic isolating mount compressible between said processor and said first
9 component.

1 18. The computer system of claim 17 wherein the input device is a mouse or a keyboard.

1 19. The computer system of claim 17 wherein said first component is a printed wiring board
2 (PWB).

1 20. The computer system of claim 17 wherein said dynamic isolating mount comprises a
2 continuous piece that contacts the periphery of said processor.